

OL-PCA8538U

Bare die; 247 bumps

10 February 2016

Package information

1. Package summary

| | |
|--------------------------------|---------------------|
| Terminal position code | U (upper) |
| Package type descriptive code | UC |
| Package type industry code | UC |
| Package style descriptive code | UC (uncased chip) |
| Package style suffix code | NA (not applicable) |
| Package body material type | X (other) |
| IEC package outline code | --- |
| JEDEC package outline code | --- |
| JEITA package outline code | --- |
| Mounting method type | S (surface mount) |
| Issue date | 7-1-2013 |

Table 1. Package summary

| Symbol | Parameter | | Min | Typ | Nom | Max | Unit |
|----------------|--------------------------------|--|-----|-----|-------|-----|------|
| D | package length | | - | - | 5.88 | - | mm |
| E | package width | | - | - | 1.2 | - | mm |
| A | seated height | | - | - | 0.4 | - | mm |
| A ₂ | package height | | - | - | 0.38 | - | mm |
| e | nominal pitch | | - | - | 0.045 | - | mm |
| n ₂ | actual quantity of termination | | - | - | 247 | - | |



2. Package outline

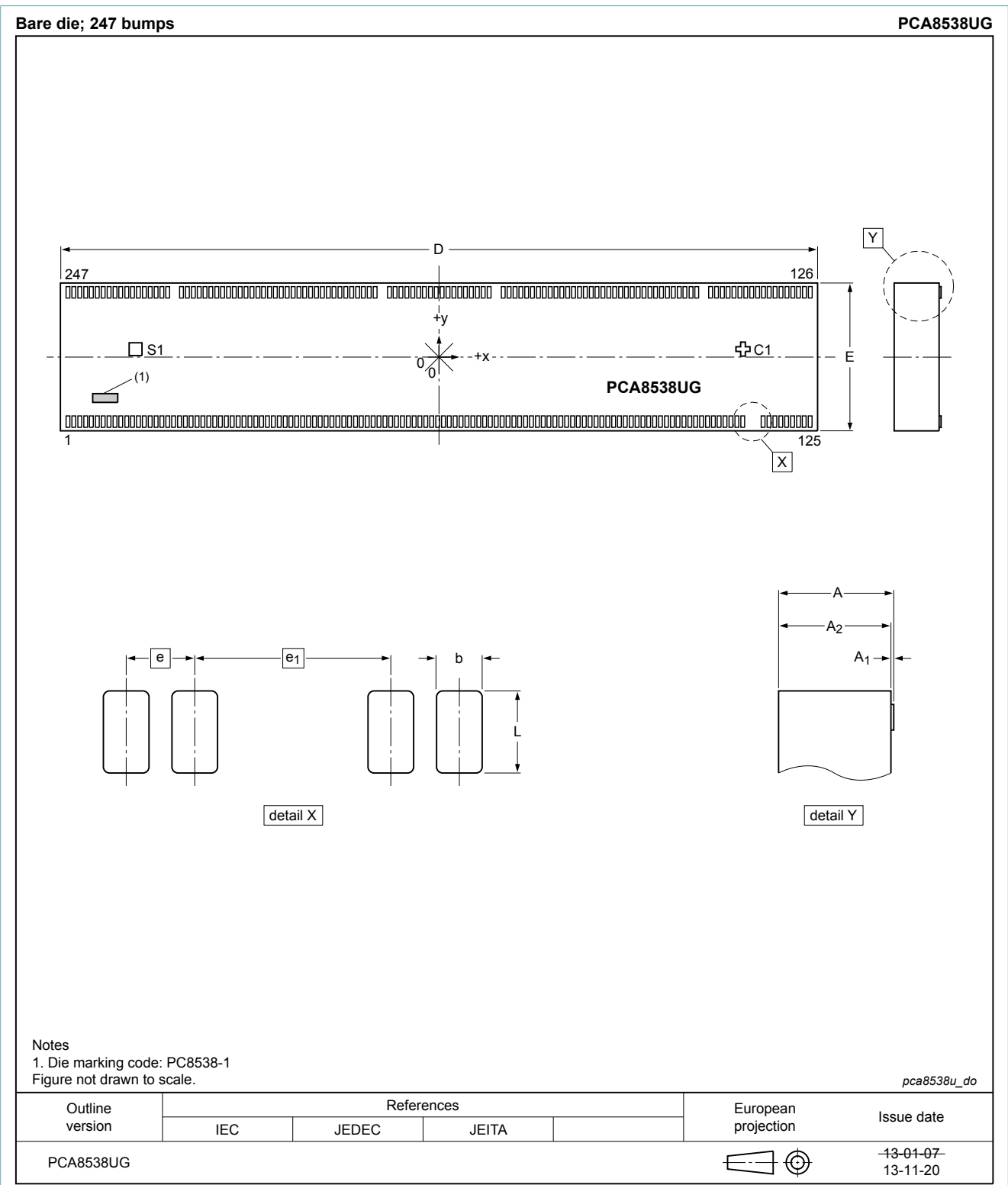


Fig. 1. Package outline UC (OL-PCA8538U)

3. Legal information

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4. Contents

1. Package summary..... 1

2. Package outline..... 2

3. Legal information..... 3

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Date of release: 10 February 2016